

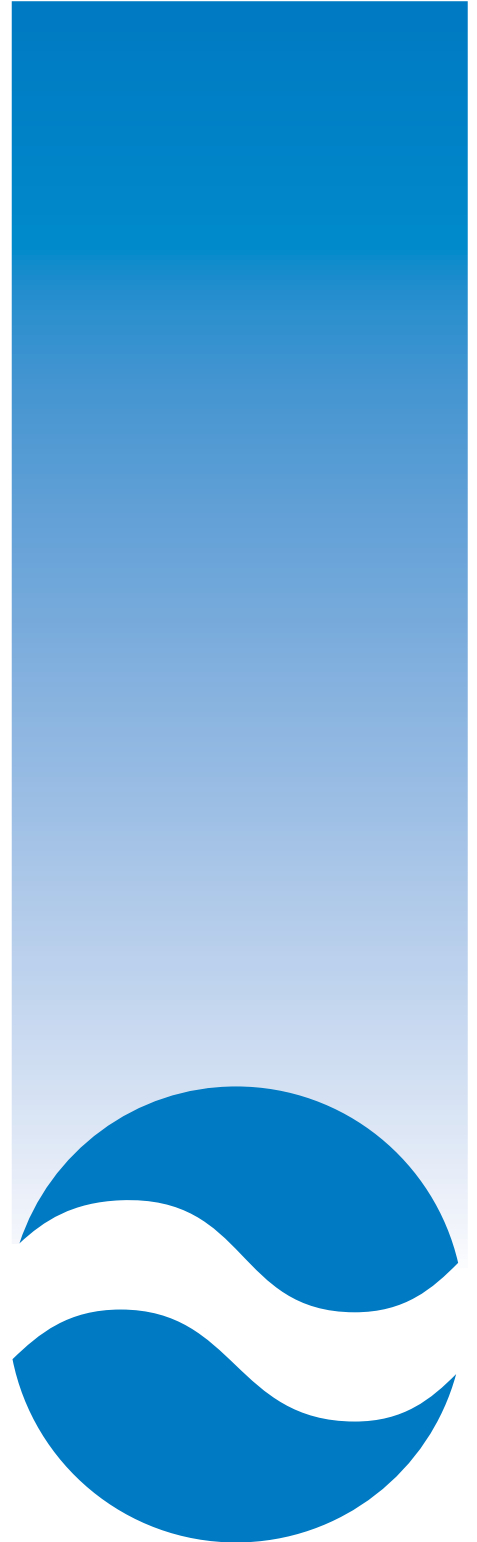
**IPC J-STD-001HS**  
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Space and Military  
Applications Electronic  
Hardware Addendum to  
IPC J-STD-001H  
Requirements for  
Soldered Electrical  
and Electronic  
Assemblies



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IPC J-STD-001HS

# **Space and Military Applications Electronic Hardware Addendum to IPC J-STD-001H Requirements for Soldered Electrical and Electronic Assemblies**

Developed by the J-STD-001 Space and Military Electronic Assemblies Task Group (5-22as) of the Assembly & Joining Committee (5-20) of IPC

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**Contact:**

IPC  
3000 Lakeside Drive, Suite 105N  
Bannockburn, Illinois  
60015-1249  
Tel 847 615.7100  
Fax 847 615.7105

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---

### Assembly and Joining Committee

Chair  
Daniel L. Foster  
Missile Defense Agency

Vice Chair  
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MacDermid Alpha Electronics Solutions

### J-STD-001 Space and Military Electronic Assemblies Task Group

Chair  
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NASA Marshall Space Flight Center

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Ekaterina Stees  
Lockheed Martin Missiles & Fire Control

### Technical Liaison of the IPC Board of Directors

Bob Neves  
Microtek (Changzhou) Laboratories

---

### Members of J-STD-001 Space and Military Electronic Assemblies Task Group\*

Kathy Johnston	Dawn Cabales, Carlisle Interconnect Technologies	Francisco Fourcade, Fourcad, Inc
Moriah Bischann	Tawsha Cabales, Carlisle Interconnect Technologies	Henrik Jensen, Gaasdal Bygningsindustri A/S
Douglas Schueller, AbelConn, LLC	Vesna Delic, Carlisle Interconnect Technologies	Melby Muckom, General Dynamics Advanced Information Systems
Neil Wolford, AbelConn, LLC	Steven Perng, Cisco Systems Inc.	Francesco Di Maio, GESTLABS S.r.l.
Ross Dillman, ACI Technologies, Inc.	Robert Priore, Cisco Systems Inc.	Lalith Bandara, GPV Lanka (Pvt) Ltd.
Constantino Gonzalez, ACME Training & Consulting	David Adams, Collins Aerospace	John Mastorides, Honeywell Aerospace
John Vickers, Advanced Rework Technology - A.R.T.	William Cardinal, Collins Aerospace	Christina Rutherford, Honeywell Aerospace
Debbie Wade, Advanced Rework Technology - A.R.T.	Caroline Ehlinger, Collins Aerospace	Hector Valladares, Honeywell Aerospace
Michael Wierleski, Aerojet Rocketdyne	David Hillman, Collins Aerospace	Keith Walker, Honeywell Aerospace
Brandy Tharp, AeroTEC Inc.	Scott Meyer, Collins Aerospace	Richard Rumas, Honeywell Canada
Chris Stuber, American Hakko Products Inc.	Timothy Pearson, Collins Aerospace	Milea Kammer, Honeywell International
Sean Keating, Amphenol Limited (UK)	Miguel Dominguez, Continental Temic SA de CV	Jennie Hwang, H-Technologies Group
Stefan Hanigk, Ariane Group GmbH	Jose Servin Olivares, Continental Temic SA de CV	Joe Hughes, Hughes Circuits, Inc.
Greg Hurst, BAE Systems	Jose Servin Olivares, Continental Temic SA de CV	Poul Juul, HYTEK
Joseph Kane, BAE Systems	Kathleen Kouthong, Crane Aerospace & Electronics	Ana Ferrari Felippi, Instituto de Pesquisas Eldorado
Kelly Kovalovsky, BAE Systems	Simon Franklin, Custom Interconnect Ltd	Ife Hsu, Intel Corporation
Agnieszka Ozarowski, BAE Systems	Monica Tucker, Dynetics, Inc.	Jose Luis Gonella, INVAP S.E.
Jonathon Vermillion, Ball Aerospace & Technologies Corp.	Gil Zilber, Elta Systems Ltd.	Emmanuelle Guene, Inventec Performance Chemicals
Gerald Bogert, Bechtel Plant Machinery, Inc.	Murilo Levy Casotti, Embraer SA	Toshiyasu Takei, Japan Unix Co., Ltd.
Samuel Sorto, Blue Origin, LLC	Leo Lambert, EPTAC Corporation	
Ryan Trussell, Blue Origin, LLC	Marcia McLaughlin, EPTAC Corporation	
Eric Harenburg, Boeing Company	Helena Pasquito, EPTAC Corporation	
	Kenneth Rahn, FCI USA, Inc.	

---

Jose Delgado, Jet Propulsion Laboratory	David Mitchell, Lockheed Martin Rotary & Mission Systems	Bruce Hughes, Nvidia Corporation
Minh Do, Jet Propulsion Laboratory	Paul Kirpes, Los Alamos National Laboratory	Gustavo Arredondo, PARA TECH Parylene Services
Reza Ghaffarian, Jet Propulsion Laboratory	Matt Garrett, Microsemi	Rob Walls, PIEK International Education Centre (I.E.C.) BV
Alan Young, Jet Propulsion Laboratory	Daniel Foster**, Missile Defense Agency (MDA)	Kirk Van Dreel, Plexus Corp.
Sue Powers-Hartman, Killdeer Mountain Manufacturing, Inc.	Edward Rios, Motorola Solutions	James Taylor, Plexus Corp.
Nancy Bullock-Ludwig, Kimball Electronics	Alvin Boutte, NASA Goddard Space Flight Center	Philip Henault, Raytheon
Augustin Stan, L&G Advice Serv SRL	Chris Fitzgerald, NASA Goddard Space Flight Center	James Daggett, Raytheon Company
Shelley Holt, L3Harris Communications	Bhanu Sood, NASA Goddard Space Flight Center	Mary Herndon, Raytheon Company
Theodore Laser, L3Harris Communications	Robert Cooke, NASA Johnson Space Center	Michael Jawitz, Raytheon Company
Peter Menuetz, L3Harris Technologies, Inc.	James Blanche, NASA Marshall Space Flight Center	Lisa Maciolek, Raytheon Company
Dominik Alder, Lockheed Martin Corporation	Charles Gamble, NASA Marshall Space Flight Center	David Pinsky, Raytheon Company
Chris Newton, Lockheed Martin Corporation	Adam Gowan, NASA Marshall Space Flight Center	James Saunders, Raytheon Company
Don Dupriest, Lockheed Martin Missiles & Fire Control	Garry McGuire, NASA Marshall Space Flight Center	Fonda Wu, Raytheon Company
Ben Gumpert, Lockheed Martin Missiles & Fire Control	Zackary Fava, NAVAIR	Matthew Abbott, Raytheon Missile Systems
Sharissa Johns, Lockheed Martin Missiles & Fire Control	William May, Naval Surface Warfare Ctr	Lance Brack, Raytheon Missile Systems
Kyle Johnson, Lockheed Martin Missiles & Fire Control	Joseph Sherfick, Naval Surface Warfare Ctr	Maria Colon, Raytheon Missile Systems
Vijay Kumar, Lockheed Martin Missiles & Fire Control	Nicholas Walton, Naval Surface Warfare Ctr	George Millman, Raytheon Missile Systems
Pamela Petcosky, Lockheed Martin Mission Systems & Training	Stephanie Stork, Northrop Grumman	Joseph Schmidt, Raytheon Missile Systems
Owen Reid, Lockheed Martin Missiles & Fire Control	Randy McNutt, Northrop Grumman Aerospace Systems	Nichole C. Thilges, Raytheon Missile Systems
Ekaterina Stees, Lockheed Martin Missiles & Fire Control	Patrick Phillips, Northrop Grumman Innovation Systems	Martin Scionti, Raytheon Vision Systems
Ann Marie Tully, Lockheed Martin Missiles & Fire Control	Ceferino Reyes, Northrop Grumman Innovation Systems	Rama Murthy PBV, Research Centre Imarat, DRDO, Ministry of Defence
Jarrold Webb, Lockheed Martin Missiles & Fire Control	Mahendra Gandhi, Northrop Grumman Space Systems	Chris Mahanna, Robisan Laboratory Inc.
Schuyler Williams, Lockheed Martin Missiles & Fire Control	Kelly Wrightsman, Northrop Grumman SSES	Gary Latta***, SAIC
	Callie Olague, Northrop Grumman Systems Corporation	Rodney Doss, Samtec, Inc.
	William Graver, NTS - Baltimore	Scott Vorhies, Space Exploration Technologies
		Jay Brusse, SSAI at NASA Goddard Space Flight Center
		Robert Fornefeld, STI Electronics, Inc.
		Patricia Scott, STI Electronics, Inc.
		Lynda Pelley, Teledyne Dalsa

---

Michael Collier, Teledyne Leeman Labs	Tapas Yagnik, TTM Technologies, Inc.	Dave Harrell, Viasat Inc.
Gaston Hidalgo, Toyota Motor North America	Paul Zutter, U.S. Army Aviation & Missile Command	Lorna Stoddart, WL Gore & Associates (UK) Ltd
Daniel Koss, TTM Technologies, Inc.	Constantin Hudon, Varitron Technologies Inc.	Zhiman Chen, Zhuzhou CRRC Times Electric Co., LTD.
James Monarchio, TTM Technologies, Inc.		Zhe (Jacky) Liu, ZTE Corporation

\* Members of the Space Electronic Assemblies J-STD-001 Addendum Task Group (5-22as) and Requirements for Military Systems Working Group (5-22ad) of the Assembly and Joining Processes Committee (5-20) merged their activities during the development of this document and are now known as 5-22as J-STD-001 Space and Military Electronic Assemblies Task Group.

\*\* Chair, 5-22ad, Requirements for Military Systems Working Group prior to merging with 5-22as.

\*\*\*Vice Chair, 5-22ad, Requirements for Military Systems Working Group prior to merging with 5-22as.

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# Space and Military Applications Electronic Hardware Addendum to IPC J-STD-001H Requirements for Soldered Electrical and Electronic Assemblies

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